

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10765931			
<b>Filing Date:</b>	29-Jan-2004			
<b>Title of Invention:</b>	Solder deposition method and solder bump forming method			
First Named Inventor/Applicant Name:	Youichi Kukimoto			
<b>Filer:</b>	Ken Sakurabayashi/Evette Ginn			
<b>Attorney Docket Number:</b>	Q79041			
Filed as Large Entity				
<b>Utility</b>	<b>Filing Fees</b>			
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$120 paid	1253	1	900	900

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				1690